## **ERB Series Specifications and Test Method (1)**

No.	o. Item		Specifications	Test Method					
1	Operating Temperature Range		-55 to +125℃	Reference Temperature: 25°C					
2	Rated Voltage		See the previous pages.	The rated voltage is defined as the maximum voltage wh may be applied continuously to the capacitor.  When AC voltage is superimposed on DC voltage, V <sup>P-P</sup> or whichever is larger, should be maintained within the rated voltage range.			je, V <sup>P-P</sup> or V <sup>O-P</sup> ,		
3	Appearar	nce	No defects or abnormalities	Visual inspection					
4	Dimensio	ns	Within the specified dimension	Using calipers					
5	Dielectric Strength		No defects or abnormalities	No failure should be observed when 300%(*) of the rated volt age is applied between the terminations for 1 to 5 seconds, provided the charge/discharge current is less than 50mA.  (*) 300V: 250%, 500V: 200%			5 seconds,		
6	Insulation Resistance (I.R.)		1,000,000MΩ min. (C≦470pF) 100,000MΩ min. (C>470pF)	The insulation resistance should be measured with a DC voltage not exceeding the rated voltage at 25°C and standard humidity and within 2 minutes of charging.					
7	Capacita	nce	Within the specified tolerance	· ·	The capacitance/Q should be measured at 25℃ at the				
8	Q		C≦ 220pF : Q≥10,000 220pF <c≦ 470pf="" 5,000<br="" :="" q≥="">470pF<c≦1,000pf 3,000<br="" :="" q≥="">C: Nominal Capacitance (pF)</c≦1,000pf></c≦>	Frequency 1±0.1MHz Voltage 1±0.2Vrms					
	Capacitance Temperature Characteristics	Capacitance Change Temperature Coefficent	Within the specified tolerance (Table A-6)  Within the specified tolerance (Table A-6)	The temperature coefficient is determined capacitance measured in step 3 as a refet the temperature sequentially from step 1 capacitance should be within the specifie					
9			Within ±0.2% or ±0.05pF (Whichever is larger)	The capacitance drift between the maximu	ent and capacitance change as Table A. It is calculated by dividing the differences um and minimum measured values in steps pacitance value in step 3.  Temperature (°C)  25±2  -55±3  25±2  125±3  25±2				
	Adhesive Strength of Termination		No removal of the terminations or other defects should occur.	Solder the capacitor	on the test iia	(glass epoxy	board) shown		
10			Solder Resist Baked Electrode or Copper Foil	Solder the capacitor on the test jig (glass epoxy board) shown in Fig. 1 using an eutectic solder.  Then apply 10N* force in parallel with the test jig for 10±1sec. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  Type a b c ERB18 1.0 3.0 1.2 ERB21 1.2 4.0 1.65 ERB32 2.2 5.0 2.9  (in mm) *5N (ERB188)					

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## **ERB Series Specifications and Test Method (1)**

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No.	lo. Item		S	pecifications	Test Method				
	Appearance		No defects or abnormalities	es	Solder the capacitor to the test jig (glass epoxy board) in the				
	С	Capacitance	Within the specified tolera	nce	same manner and under the same conditions as (10).				
11	bration esistance	2	Satisfies the initial value.  C≤ 220pF : Q≥1 220pF <c≤ (<="" 470pf="" 470pf<c≤1,000pf="" :="" c:="" capacitance="" nominal="" q≥="" td=""><td>5,000 3,000</td><td colspan="5">The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 minute. This motion should be applied for a period of 2 hours in each of 3 mutually perpendicular directions (total of 6 hours).</td></c≤>	5,000 3,000	The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 minute. This motion should be applied for a period of 2 hours in each of 3 mutually perpendicular directions (total of 6 hours).				
12 De	Deflection		No crack or marked defect speed:  20 50 Pressurize speed:  Pressurize Pressurize speed:  Capacitance meter 45 45 Fig.3a	izing 1.0mm/sec.	Solder the capacitor on the test jig (glass epoxy board) shown in Fig. 2a using an eutectic solder. Then apply a force in the direction shown in Fig. 3a. The soldering should be done by the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  Type a b c ERB18 1.0 3.0 1.2 ERB21 1.2 4.0 1.65 ERB32 2.2 5.0 2.9  (in mm)				
	olderabilit erminatior		95% of the terminations are continuously.	e to be soldered evenly and	Immerse the capacitor in a solution of isopropyl alcohol and rosin (25% rosin in weight proportion).  Preheat at 80 to 120°C for 10 to 30 seconds.  After preheating, immerse in an eutectic solder or Sn-3.0Ag-0.5Cu solder solution for 5±0.5 seconds at 245±5°C.				
14	Resistance to Soldering Heat		The measured and obser specifications in the follow  Item Appearance Capacitance Change  Q  Dielectric Strength	ved characteristics should satisfy the ring table.  Specifications  No marked defect  Within ±2.5% or ±0.25pF  (Whichever is larger)  C≤ 220pF : Q≥10,000  220pF <c≤ (pf)<="" 3,000="" 470pf="" 470pf<c≤1,000pf="" 5,000="" :="" c:="" capacitance="" failure="" no="" nominal="" q≥="" td=""><td colspan="5">Preheat according to the conditions listed in the table below.  Immerse the capacitor in an eutectic solder or Sn-3.0Ag-0.5Cu solder solution at 270±5°C for 10±0.5 seconds. Let sit at room temperature for 24±2 hours.    Chip Size   Preheat Condition     2.0×1.25mm max.   1minute at 120 to 150°C     3.2×2.5mm   Each 1 minute at 100 to 120°C and then 170 to 200°C</td></c≤>	Preheat according to the conditions listed in the table below.  Immerse the capacitor in an eutectic solder or Sn-3.0Ag-0.5Cu solder solution at 270±5°C for 10±0.5 seconds. Let sit at room temperature for 24±2 hours.    Chip Size   Preheat Condition     2.0×1.25mm max.   1minute at 120 to 150°C     3.2×2.5mm   Each 1 minute at 100 to 120°C and then 170 to 200°C				
15	Temperature Cycle		The measured and obser specifications in the follow  Item Appearance Capacitance Change  Q  I.R. Dielectric Strength	ved characteristics should satisfy the ving table.  Specifications  No marked defect  Within $\pm 5\%$ or $\pm 0.5$ pF  (Whichever is larger) $C \ge 30$ pF : $Q \ge 350$ $10$ pF $\le C < 30$ pF : $Q \ge 275 + \frac{5}{2}$ C $C < 10$ pF : $Q \ge 200 + 10$ C  1,000M $\Omega$ min.  No failure	Fix the capacitor to the supporting jig in the same manner and under the same conditions as (10). Perform the five cycles according to the four heat treatments listed in the following table. Let sit for 24±2 hours at room temperature, then measure.    Step				
16 Hu			The measured and obser specifications in the follow Item Appearance Capacitance Change Q I.R.	C: Nominal Capacitance (pF)  ved characteristics should satisfy the ring table.  Specifications  No marked defect  Within ±5% or ±0.5pF (Whichever is larger)  C≥30pF: Q≥350  10pF≤C<30pF: Q≥275+ ½ C  C<10pF: Q≥200+10C  1,000MΩ min.  C: Nominal Capacitance (pF)	Apply the 24-hour heat (-10 to +65°C) and humidity (80 to 100%) treatment shown below, 10 consecutive times. Remove, let sit for 24±2 hours at room temperature, and measure.  To Humidity 80-98% Humidity 80-98% Humidity 80-98% Humidity 80-98% Humidity 90-98% Humidity 90-				

-- Hours

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No.	Item	S	pecifications	Test Method		
		The measured and obser specifications in the follow	Specifications			
17	High Temperature Load	Appearance Capacitance Change	No marked defect Within ±3% or ±0.3pF (Whichever is larger)	Apply 200% (500V only 150%) of the rated voltage for 1,000±1 hours at 125±3°C.		
.,		Q	C≥30pF : Q≥350 10pF≤C<30pF : Q≥275+ ½ C C<10pF : Q≥200+10C	Remove and let sit for 24±2 hours at room temperature, then meas The charge/discharge current is less than 50mA.		
		I.R.	1,000MΩ min.			
			C: Nominal Capacitance (pF)			

## Table A-6

	Nominal Values (ppm/°C) Note 1	Capacitance Change from 25°C (%)					
Char.		<b></b> 55		-30		-10	
		Max.	Min.	Max.	Min.	Max.	Min.
5C	0±30	0.58	-0.24	0.40	-0.17	0.25	-0.11

Note 1: Nominal values denote the temperature coefficient within a range of 25 to 125°C (for 5C)